

CLAIMS

1. A resist composition comprising (A) a resin component, (B) a photopolymerization initiator, (C) water and (D) an organic solvent, wherein the organic solvent
5 (D) contains:
 - (D-1) at least one organic solvent selected from the group consisting of an α -hydroxycarboxylate ester, a β -alkoxycarboxylate ester, a 1,3-diol compound and a 1,3-diol compound derivative, and
 - 10 (D-2) an organic solvent having a hydroxyl group other than (D-1).
2. The resist composition according to claim 1, wherein (D-1) is an α -hydroxycarboxylate ester.
3. The resist composition according to claim 2,
15 wherein the α -hydroxycarboxylate ester is a lactate ester.
4. A method of producing a resist-coated substrate, which comprises dipping an insulating substrate comprising a conductive metal in the resist
20 composition according to any one of claims 1 to 3.
5. A method of producing a print circuit board, which comprises using the resist composition according to any one of claims 1 to 3.
6. A resist composition for dip coating comprising
25 (A) a resin component, (B) a photopolymerization initiator, (C) water and (D) an organic solvent, wherein the organic solvent (D) contains:
 - (D-1) at least one organic solvent selected from the group consisting of an α -hydroxycarboxylate ester, a β -alkoxycarboxylate ester, a 1,3-diol compound and a 1,3-diol compound derivative.
7. A method of producing a resist-coated substrate, which comprises dipping an insulating substrate comprising a conductive metal in the resist
35 composition according to claim 6.

8. A method of producing a print circuit board, which comprises using the resist composition according to claim 6.